

**SEMICONDUCTOR LASER MODULE**

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**Abstract**

**PROBLEM TO BE SOLVED:** To provide a semiconductor laser module provided with constitution capable of simply performing bonding work.

**SOLUTION:** In the semiconductor laser module 1, a prism 4 and a sub-mount 6 are arranged on a surface 3a of a semiconductor substrate 3. A reflection film 5 is formed on the slope of the prism 4, and a semiconductor laser chip 7 is mounted on the surface 6a of the sub-mount 6 opposite to that, and a monitoring photodiode chip 8 is mounted on the rear of the semiconductor laser chip 7. Signal processing photodiodes 91 to 95 are made into the semiconductor substrate surface 6a, and the central photodiode 91 is placed just under the reflection film 5. Since terminal pads 11 formed on the semiconductor substrate surface 3a, and the semiconductor laser chip 7 and photodiode chip 8 mounted on the sub-mount surface 6a are placed on parallel planes, the wire bonding work for electrically connecting them to the outside is performed simply and with a good yield.



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